

STP6NB80 STP6NB80FP

N - CHANNEL 800V - 1.6 Ω - 5.7A - TO-220/TO-220FP PowerMESH™ MOSFET

PRELIMINARY DATA

TYPE	V _{DSS}	R _{D(on)}	I _D
STP6NB80	800 V	< 1.9 Ω	5.7 A
STP6NB80FP	800 V	< 1.9 Ω	5.7 A

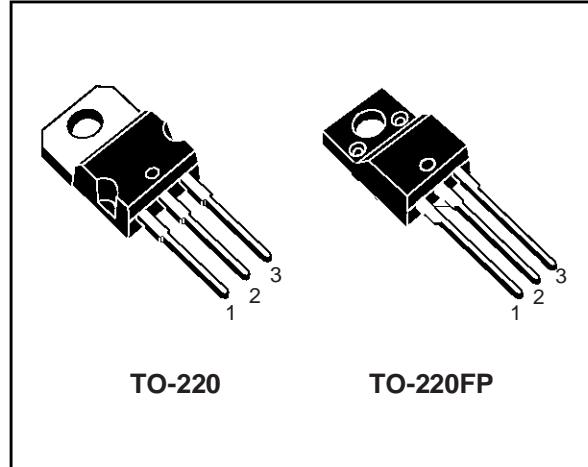
- TYPICAL R_{D(on)} = 1.6 Ω
- EXTREMELY HIGH dv/dt CAPABILITY
- 100% AVALANCHE TESTED
- VERY LOW INTRINSIC CAPACITANCES
- GATE CHARGE MINIMIZED

DESCRIPTION

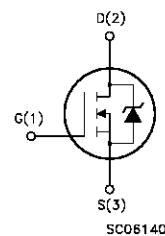
Using the latest high voltage MESH OVERLAY™ process, STMicroelectronics has designed an advanced family of power MOSFETs with outstanding performances. The new patent pending strip layout coupled with the Company's proprietary edge termination structure, gives the lowest R_{D(on)} per area, exceptional avalanche and dv/dt capabilities and unrivalled gate charge and switching characteristics.

APPLICATIONS

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITCH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DRIVE



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value		Unit
		STP6NB80	STP6NB80FP	
V _{DS}	Drain-source Voltage (V _{GS} = 0)	800		V
V _{DGR}	Drain-gate Voltage (R _{GS} = 20 kΩ)	800		V
V _{GS}	Gate-source Voltage	± 30		V
I _D	Drain Current (continuous) at T _c = 25 °C	5.7	5.7(*)	A
I _D	Drain Current (continuous) at T _c = 100 °C	3.6	2	A
I _{DM(•)}	Drain Current (pulsed)	22.8	22.8	A
P _{tot}	Total Dissipation at T _c = 25 °C	125	40	W
	Derating Factor	1.0	0.32	W/°C
dv/dt(1)	Peak Diode Recovery voltage slope	4	4	V/ns
V _{ISO}	Insulation Withstand Voltage (DC)	—	2000	V
T _{stg}	Storage Temperature	-65 to 150		°C
T _j	Max. Operating Junction Temperature	150		°C

(*) Pulse width limited by safe operating area

(1) I_{SD} ≤ 5.76 A, di/dt ≤ 200 A/μs, V_{DD} ≤ V_{(BR)DSS}, T_j ≤ T_{JMAX}

(*) Limited only maximum temperature allowed

STP6NB80/FP

THERMAL DATA

			TO-220	TO220-FP	
R _{thj-case}	Thermal Resistance Junction-case	Max	1.0	3.1	°C/W
R _{thj-amb} R _{thc-sink} T _I	Thermal Resistance Junction-ambient Thermal Resistance Case-sink Maximum Lead Temperature For Soldering Purpose	Max Typ	62.5 0.5 300	0.5 300	°C/W °C/W °C

AVALANCHE CHARACTERISTICS

Symbol	Parameter	Max Value	Unit
I _{AR}	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T _j max)	5.7	A
E _{AS}	Single Pulse Avalanche Energy (starting T _j = 25 °C, I _D = I _{AR} , V _{DD} = 50 V)	314	mJ

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source Breakdown Voltage	I _D = 250 μA V _{GS} = 0	800			V
I _{DSS}	Zero Gate Voltage Drain Current (V _{GS} = 0)	V _{DS} = Max Rating V _{DS} = Max Rating T _c = 125 °C			1 50	μA μA
I _{GSS}	Gate-body Leakage Current (V _{DS} = 0)	V _{GS} = ± 30 V			± 100	nA

ON (*)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} I _D = 250 μA	3	4	5	V
R _{D(on)}	Static Drain-source On Resistance	V _{GS} = 10V I _D = 3 A		1.6	1.9	Ω
I _{D(on)}	On State Drain Current	V _{DS} > I _{D(on)} × R _{D(on)max} V _{GS} = 10 V	5.7			A

DYNAMIC

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
g _{fs} (*)	Forward Transconductance	V _{DS} > I _{D(on)} × R _{D(on)max} I _D = 3 A	2.5	4.5		S
C _{iss} C _{oss} C _{rss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	V _{DS} = 25 V f = 1 MHz V _{GS} = 0		1250 145 16	1625 190 21	pF pF pF

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$ t_r	Turn-on Time Rise Time	$V_{DD} = 400 \text{ V}$ $I_D = 3 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$		19 9	27 13	ns ns
Q_g Q_{gs} Q_{gd}	Total Gate Charge Gate-Source Charge Gate-Drain Charge	$V_{DD} = 640 \text{ V}$ $I_D = 6 \text{ A}$ $V_{GS} = 10 \text{ V}$		33 11 14	47	nC nC nC

SWITCHING OFF

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$t_{r(V_{off})}$ t_f t_c	Off-voltage Rise Time Fall Time Cross-over Time	$V_{DD} = 640 \text{ V}$ $I_D = 6 \text{ A}$ $R_G = 4.7 \Omega$ $V_{GS} = 10 \text{ V}$		11 9 16	16 13 23	ns ns ns

SOURCE DRAIN DIODE

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
I_{SD} $I_{SDM}(\bullet)$	Source-drain Current Source-drain Current (pulsed)				5.7 22.8	A A
$V_{SD} (\ast)$	Forward On Voltage	$I_{SD} = 6 \text{ A}$ $V_{GS} = 0$			1.6	V
t_{rr} Q_{rr} I_{RRM}	Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current	$I_{SD} = 6 \text{ A}$ $di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 100 \text{ V}$ $T_j = 150 \text{ }^\circ\text{C}$		700 5.8 16.5		ns μC A

(\ast) Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %

(\bullet) Pulse width limited by safe operating area